



PRODUCT CHANGE NOTICE

PCN-2456 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
29 th May, 2020	29 th August, 2020	Discrete Semiconductors	Additional Assembly & Test Site / Assembly Bill of Materials / Additional Wafer Source / Part Top Marking	2456
TITLE				
Qualification of Internal "Diodes Technology (Cheng Du) Company Limited" (CAT) as an Additional Assembly & Test Site Using Copper or Palladium Coated Copper Bond Wire with Standardization of Assembly Bill of Materials, Or as an Additional Wafer Plating, Back Grinding and Back Metal Process Source, and Qualification of Additional Wafer Source for Select Discrete Products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified internal "Diodes Technology (Cheng Du) Company Limited" (CAT) located in Chengdu, China as an additional Assembly and Test site using copper or palladium coated copper (PdCu) bond wire with standardization of assembly bill of materials, or as an additional wafer UBM plating, back grinding and back metal process facility for select products listed in tables below. In addition, Diodes has also qualified "Diodes internal BCD (Shanghai) Micro-Electronics Limited" (SFAB2) in Shanghai China as an alternate internal wafer source for select products listed in this PCN.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification / reliability report (embedded in this file).</p>				
IMPACT				
Continuity of Supply. No change in data sheet electrical parameters and product performance. Some packages will have top marking changes as outlined in the tables below.				
PRODUCTS AFFECTED				
<p>Please see the attached part list below in following Tables:</p> <p>Table 1 – Affected Part List to add CAT as an additional A/T site using Cu or PdCu bond wire with standardization of assembly bill of materials.</p> <p>Table 2 – Affected Part List to add CAT as an additional wafer UBM plating, back grinding and back metal process facility.</p> <p>Table 3 – Affected Part List to add SFAB2 as an alternate wafer source.</p> <p>Table 4 - Mark Code Format – SOD-123 Table 5 - Mark Code Format – SOD-323 Table 6 - Mark Code Format – SOT-23 Table 7 - Mark Code Format – SOT-26 Table 8 - Mark Code Format – SOT-323 Table 9 - Mark Code Format – SOT-363 Table 10 - Mark Code Format – SOT-523 Table 11 - Mark Code Format – PowerDI3333 Table 12 - Mark Code Format – DFN1006</p>				

WEB LINKS	
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/
For More Information Contact:	http://www.diodes.com/contacts
Data Sheet:	http://www.diodes.com/products
DISCLAIMER	
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.	

Table 1 - Affected Part List to add CAT as an additional A/T site using Cu or PdCu bond wire with standarization of assembly bill of materials					
1N4448HWS-7-G	DMN10H120SFG-7	DMN3018SFG-7	DMP2007UFG-13	DMP4013LFG-13	DMT4011LFG-13
BCR420UW6-7	DMN10H170SFG-13	DMN3025LFG-13	DMP2007UFG-7	DMP4013LFG-7	DMT4011LFG-7
DMG7401SFG-13	DMN10H170SFG-7	DMN3025LFG-7	DMP2008UFG-13	DMP4025SFG-13	DMT6008LFG-13
DMG7401SFG-7	DMN2005UFG-13	DMN4008LFG-13	DMP2008UFG-7	DMP4025SFG-7	DMT6008LFG-7
DMG7408SFG-13	DMN2005UFG-7	DMN4008LFG-7	DMP2010UFG-7	DMP6023LFG-13	DMT6009LFG-7
DMG7408SFG-7	DMN3008SFG-13	DMN4010LFG-7	DMP26M7UFG-13	DMP6023LFG-7	DMT6010LFG-13
DMG7430LFG-13	DMN3008SFG-7	DMN6013LFG-7	DMP26M7UFG-7	DMP6050SFG-13	DMT6010LFG-7
DMG7430LFG-7	DMN3009SFG-13	DMN6069SFG-13	DMP3008SFG-7	DMP6050SFG-7	DMT8012LFG-7
DMG7702SFG-13	DMN3009SFG-7	DMN6069SFG-7	DMP3017SFG-13	DMS3012SFG-13	FMMT491ATA
DMG7702SFG-7	DMN3010LFG-13	DMN7022LFG-7	DMP3017SFG-7	DMS3014SFG-13	FMMT491ATC
DMN10H099SFG-13	DMN3010LFG-7	DMP2006UFG-13	DMP3035SFG-7	DMS3014SFG-7	VN10LFTA
DMN10H099SFG-7	DMN3018SFG-13	DMP2006UFG-7	DMP3036SFG-7	DMT2004UFG-7	ZXMN6A07FTA
DMN10H120SFG-13					

Table 2 – Affected Part List to add CAT as an additional wafer UBM plating, back grinding and back metal process facility					
DMN1002UCA6-7	DMN1006UCA6-7	DMN12M7UCA10-7	DMN15M3UCA6-7	DMN16M0UCA6-7	DMN16M9UCA6-7
DMN1003UCA6-7	DMN12M3UCA6-7	DMN13M9UCA6-7			

Table 3 – Affected Part List to add SFAB2 as an alternate wafer source					
DMN5L06DMK-7	DMN5L06K-7	DMN5L06WK-7	DMN61D9UDW-13	DMN61D9UW-13	DMN61D9UW-7
DMN5L06DWK-7	DMN5L06TK-7	DMN61D9U-7	DMN61D9UDW-7		

Table 4 - Mark Code Format –SOD-123

SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Add “-”on Y for CAT site
Marking format example	Marking format example

Table 5 - Mark Code Format –SOD-323

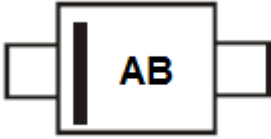
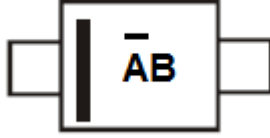
SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Add “-”on first character for CAT site
Marking format example	Marking format example
	

Table 6 - Mark Code Format –SOT-23

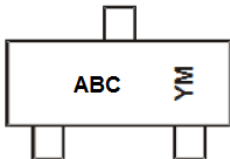
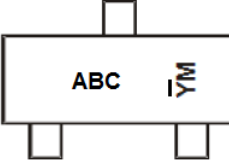
SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Add “-”on Y for CAT site
Marking format example	Marking format example
	

Table 7 - Mark Code Format –SOT-26

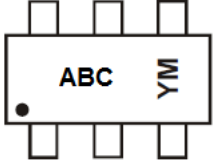
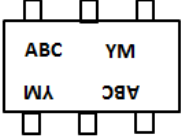
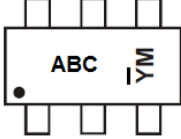
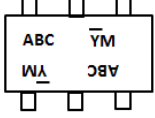
SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Add “-”on Y for CAT site		
Marking format example	Marking format example		
			

Table 8 - Mark Code Format –SOT-323

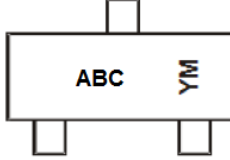
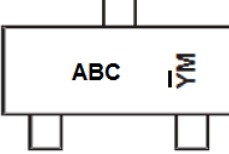
SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Add “-”on Y for CAT site
Marking format example	Marking format example
	

Table 9 - Mark Code Format –SOT-363

SAT (Diodes Internal AT site Shanghai, China)		CAT (Diodes Internal AT Site Chengdu, China) Add “-”on Y for CAT site	
Marking format example		Marking format example	

Table 10 - Mark Code Format –SOT-523

SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Add “-”on Y for CAT site
Marking format example	Marking format example

Table 11 - Mark Code Format –PowerDI3333

SAT (Diodes Internal AT site Shanghai, China)	CAT (Diodes Internal AT Site Chengdu, China) Change from YM to YWX for CAT site
Marking format example	Marking format example

Remark: YWX is date code

Y is year code:0~9


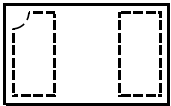

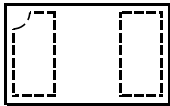

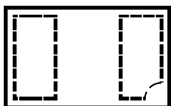

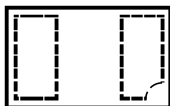

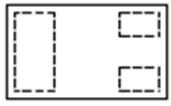

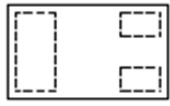
W is week code:1~26 use A~Z to display

27--53 use a~z, z displayed 52 and 53 week

X is internal code: lot schedule start date

	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Green	T	U	V	W	X	Y	Z
Lead Free	t	u	v	w	x	y	z

Table 12 - Mark Code Format –DFN1006

SAT (Diodes Internal AT site Shanghai, China)		CAT (Diodes Internal AT Site Chengdu, China) Add “-” on first character for CAT site	
Marking orientation photo (Plan Form, Perspective - from top to bottom)		Marking orientation photo (Plan Form, Perspective - from top to bottom)	
DFN1006-2, DFN1006H4-2		DFN1006-2, DFN1006H4-2	
1. DFN1006-2, DFN1006H4-2, -7,-7B suffix marking orientation		1. DFN1006-2, DFN1006H4-2, -7,-7B suffix marking orientation	
 (Top)	 (Perspective)	 (Top)	 (Perspective)
2. DFN1006-2, DFN1006H4-2, -7,-7B suffix marking orientation		2. DFN1006-2, DFN1006H4-2, -7,-7B suffix marking orientation	
 (Top)	 (Perspective)	 (Top)	 (Perspective)
DFN1006-3		DFN1006-3	
1.DFN1006-3,DFN1006H4-3, -7B suffix marking orientation		1.DFN1006-3,DFN1006H4-3, -7B suffix marking orientation	
 (Top)	 (Perspective)	 (Top)	 (Perspective)